

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
650V	$3.8\Omega@10V$	2A

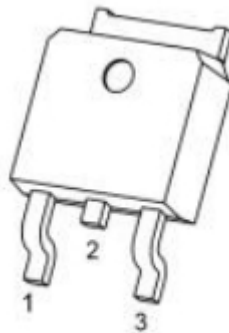
Feature

- Fast Switching
- Low Gate Charge and $R_{DS(on)}$
- 100% Single Pulse avalanche energy Test

Application

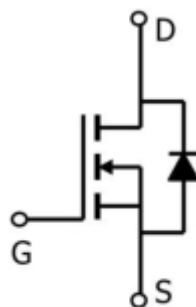
- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package

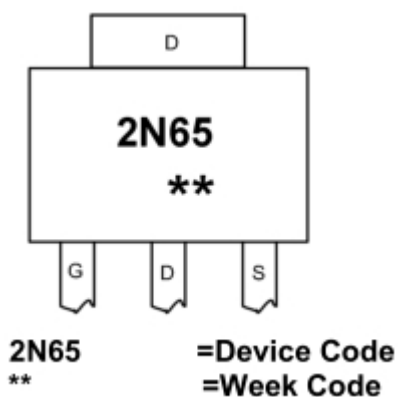


TO-252(G:1 D:2 S:3)

Circuit diagram



Marking



Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	650	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current ¹ (T _C =25°C)	I _D	2	A
Pulsed Drain Current ²	I _{DM}	8	A
Single Pulse Avalanche Energy ³	E _{AS}	140	mJ
Total Power Dissipation(T _C =25°C)	P _D	44	W
Thermal Resistance Junction-Case ¹	R _{θJC}	2.84	°C/ W
Storage Temperature Range	T _{STG}	-55~ +150	°C
Operating Junction Temperature Range	T _J	-55~ +150	°C

Electrical characteristics

($T_A=25^{\circ}\text{C}$, unless otherwise noted)

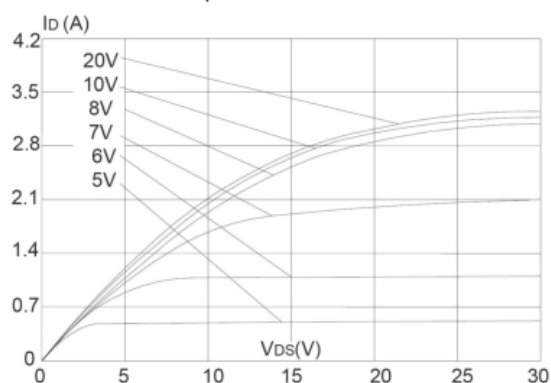
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	650			V
Bvdss Temperature Coefficient	ΔBVDSS/ΔTJ	I _D =250uA,Reference25 °C		0.4		V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =520V,V _{GS} = 0V T _J =25°C			10	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±100	uA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Static Drain-Source on-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =1A		3.8	4.8	Ω
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1MHz		270		pF
Output Capacitance	C _{oss}			41		
Reverse Transfer Capacitance	C _{rss}			5		
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =480V, V _{GS} =10V, I _D =2A		9		nC
Gate-Source Charge	Q _{gS}			1.7		
Gate-Drain Charge	Q _{gd}			4		
Turn-On Delay Time	T _{d(on)}	V _{DD} =300V, V _{GS} =10V, R _G =25 Ω, I _D =2A		11		nS
Rise Time	T _r			25		
Turn-Off Delay Time	T _{d(off)}			22		
Fall Time	T _f			24		

Notes:

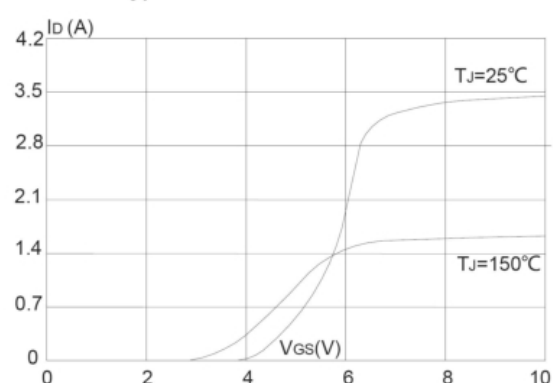
- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $R_G = 25\Omega$, $L = 64\text{mH}$, $V_{DD} = 50V$

Typical Characteristics

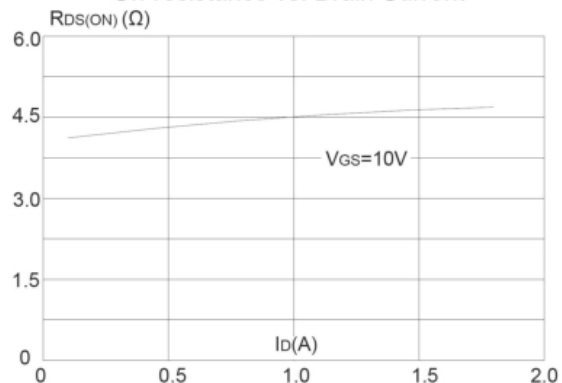
Output Characteristics



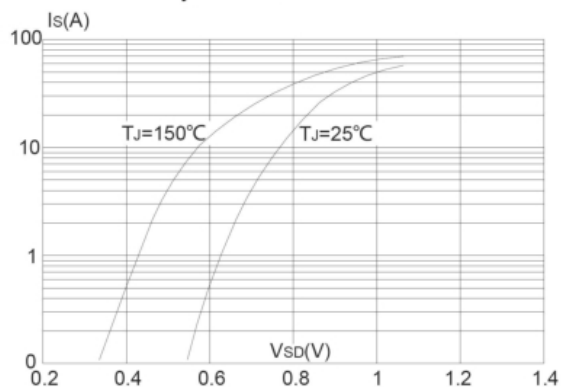
Typical Transfer Characteristics



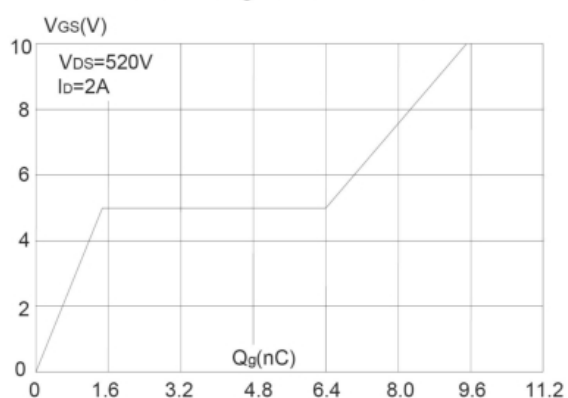
On-resistance vs. Drain Current



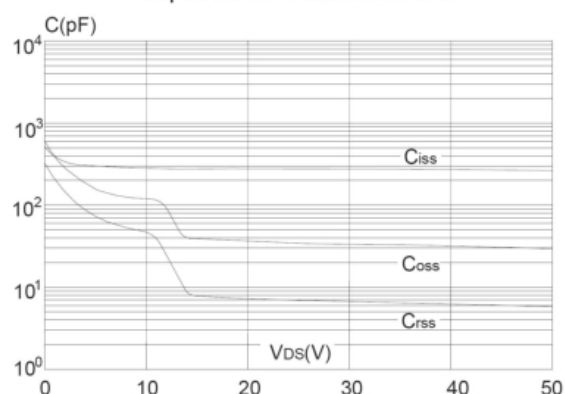
Body Diode Characteristics



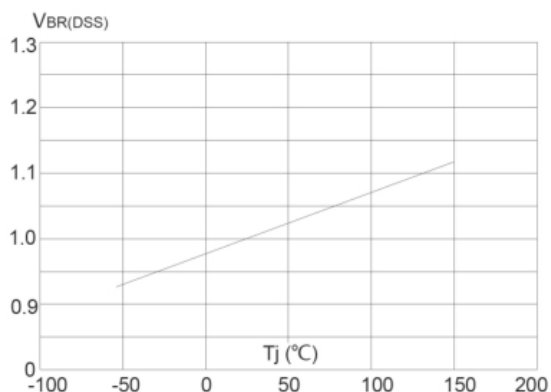
Gate Charge Characteristics



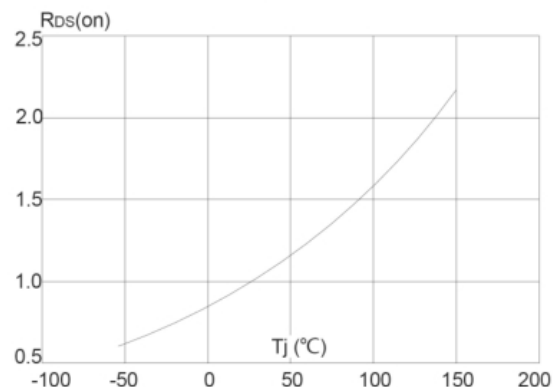
Capacitance Characteristics



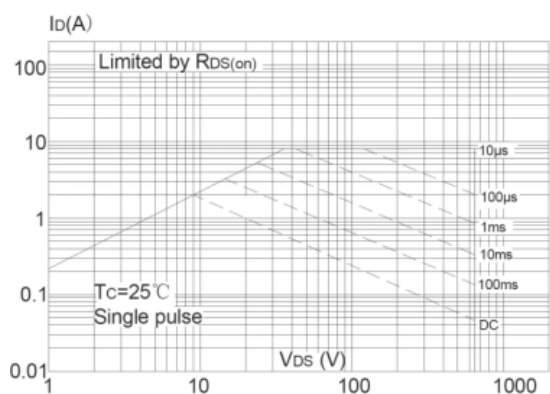
Normalized Breakdown Voltage vs. Junction Temperature



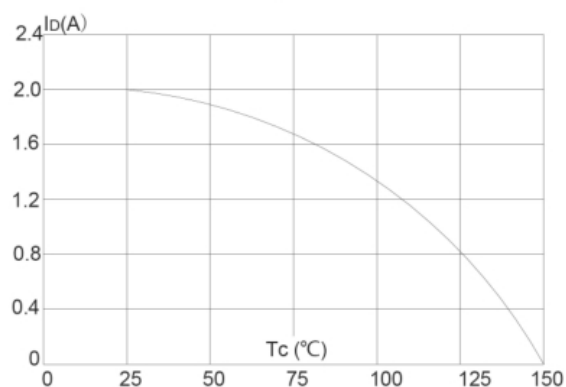
Normalized on Resistance vs. Junction Temperature



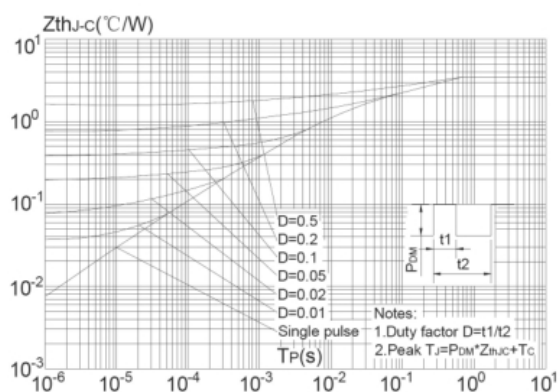
Maximum Safe Operating Area



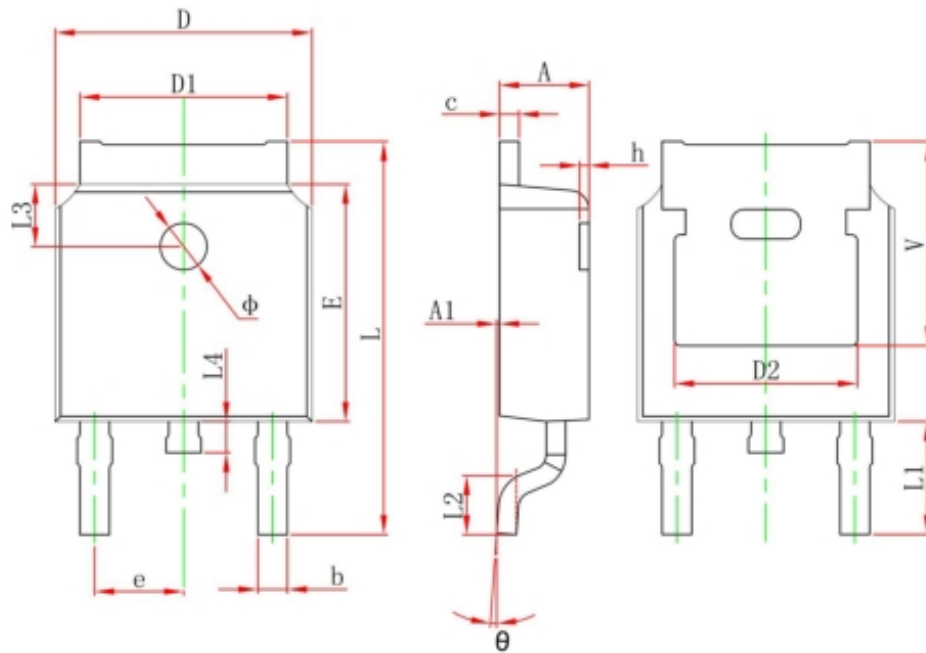
Maximum Continuous Drain Current vs. Case Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Case



OT-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	